



N-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	$R_{DS(on)}$ (Ω)	I _D (A) ^a	Q _g (Typ.)		
30	0.0046 at V _{GS} = 10 V	19.8	36 nC		
	0.0054 at V _{GS} = 4.5 V	18.2	30 110		

SO-8 S 1 8 D S 2 7 D S 3 6 D Top View

Ordering Information: Si4362BDY-T1-E3 (Lead-(Pb)-free)

Si4362BDY-T1-GE3 (Lead-(Pb)-free and Halogen-free)

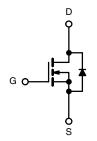
FEATURES

- Halogen-free According to IEC 61249-2-21 Available
- TrenchFET[®] Power MOSFET
- Optimized for "Low Side" Synchronous Rectifier Operation
- 100 % R_g Tested

ROHS COMPLIANT HALOGEN FREE Available

APPLICATIONS

- DC/DC Converters
- Synchronous Rectifiers



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS	$T_A = 25$ °C, unle	ss otherwise no	oted		
Parameter	Symbol	Limit	Unit		
Drain-Source Voltage		V _{DS}	30	V	
Gate-Source Voltage		V _{GS}	± 12]	
	T _C = 25 °C		29		
Continuous Drain Current (T. 150 °C)	T _C = 70 °C		23		
Continuous Drain Current (T _J = 150 °C)	T _A = 25 °C	l _D –	19.8 ^{b, c}		
	T _A = 70 °C	1	15.8 ^{b, c}	А	
Pulsed Drain Current		I _{DM}	60		
Continuous Course Drain Diade Current	T _C = 25 °C	,	6		
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	2.7 ^{b, c}		
	T _C = 25 °C		6.6		
Mariana Bana Birainatia	T _C = 70 °C		4.2		
Maximum Power Dissipation	T _A = 25 °C	P _D	3.0 ^{b, c}	W	
	T _A = 70 °C		2 ^{b, c}		
Operating Junction and Storage Temperature Ra	T _J , T _{stg}	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS						
Parameter	Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient ^{b, d}	t ≤ 10 s	R _{thJA}	34	41	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	15	19	- C/VV	

Notes:

- a. Based on T_C = 25 °C.
- b. Surface Mounted on 1" x 1" FR4 board.
- c. t = 10 s
- d. Maximum under Steady State conditions is 80 $^{\circ}\text{C/W}.$

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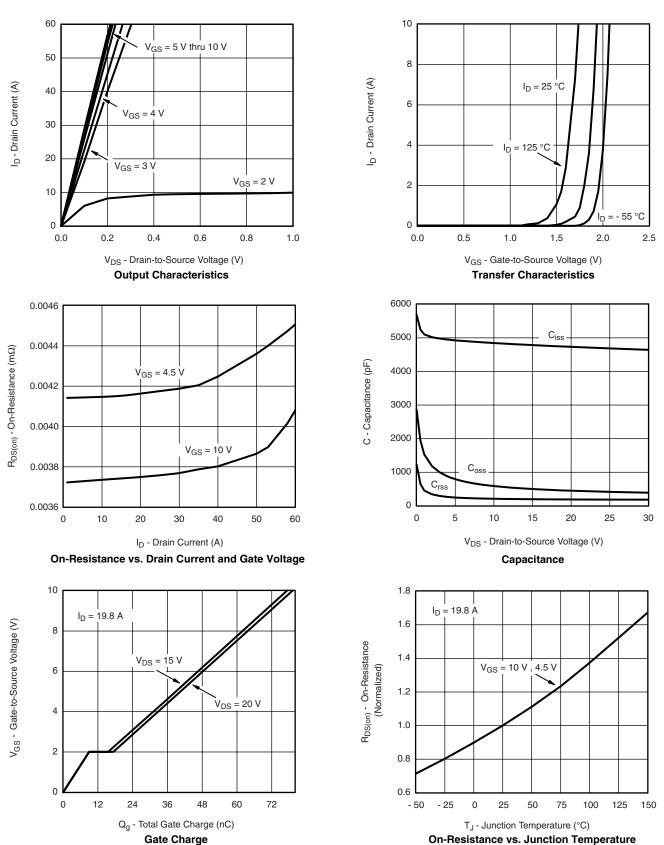
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static				1 - 7	1		
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = 1 mA	30			٧	
V _{DS} Temperature Coefficient	ΔV _{DS} /T _J			31.4		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA		- 4.9			
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	0.6		2.0	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 12 \text{ V}$			± 100	nA	
Zero Gate Voltage Drain Current	465	V _{DS} = 30 V, V _{GS} = 0 V			1	μΑ	
	I _{DSS}	V _{DS} = 30 V, V _{GS} = 0 V, T _J = 55 °C			10		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	30			Α	
		V _{GS} = 10 V, I _D = 19.8 A		0.0038	0.0046	Ω	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 4.5 V, I _D = 18.2 A		0.0043	0.0054		
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 19.8 A		120		S	
Dynamic ^b	-				L	I	
Input Capacitance	C _{iss}			4800		pF	
Output Capacitance	C _{oss}	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		500			
Reverse Transfer Capacitance	C _{rss}			200			
Total Cata Charge		$V_{DS} = 15 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 19.8 \text{ A}$		75	115		
Total Gate Charge	Q _g			36	54		
Gate-Source Charge	Q_{gs}	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 19.8 \text{ A}$		9			
Gate-Drain Charge	Q_{gd}			6.5			
Gate Resistance	R_g	f = 1 MHz		1.05	1.6	Ω	
Turn-On Delay Time	t _{d(on)}			26	40		
Rise Time	t _r	V_{DD} = 15 V, R_L = 1.5 Ω		11	20		
Turn-Off Delay Time	t _{d(off)}	$I_D\cong$ 10 A, V_{GEN} = 4.5 V, R_g = 1 Ω		41	65		
Fall Time	t _f			7	15	no	
Turn-On Delay Time	t _{d(on)}			12	20	ns	
Rise Time	t _r	V_{DD} = 15 V, R_L = 1.5 Ω		10	15		
Turn-Off Delay Time	t _{d(off)}	$I_D \cong$ 10 A, V_{GEN} = 10 V, R_g = 1 Ω		47	70		
Fall Time	t _f			8	15		
Drain-Source Body Diode Characteristic	cs						
Continuous Source-Drain Diode Current	I _S	$T_C = 25 ^{\circ}C$			6	Α	
Pulse Diode Forward Current ^a	I _{SM}				60) ^	
Body Diode Voltage	V _{SD}	I _S = 5 A		0.7	1.1	V	
Body Diode Reverse Recovery Time	t _{rr}			35	60	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	I _F = 10 A, dl/dt = 100 A/μs, T _J = 25 °C		30	60	nC	
Reverse Recovery Fall Time	t _a			18			
Reverse Recovery Rise Time	t _b			17		ns	

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



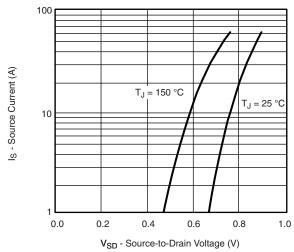
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



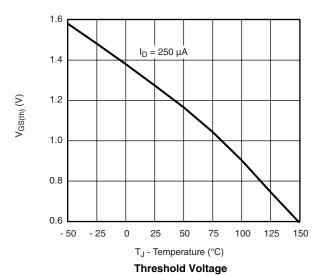
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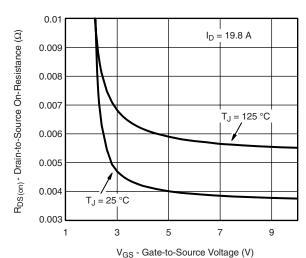
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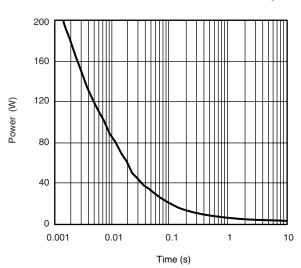


Source-Drain Diode Forward Voltage

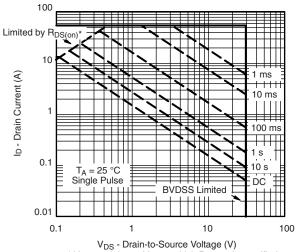




On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power



* V_{GS} > minimum V_{GS} at which R_{DS(on)} is specified

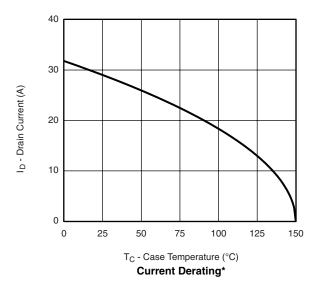
Safe Operating Area, Junction-to-Ambient

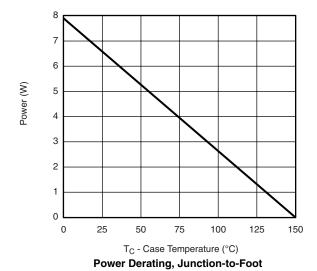






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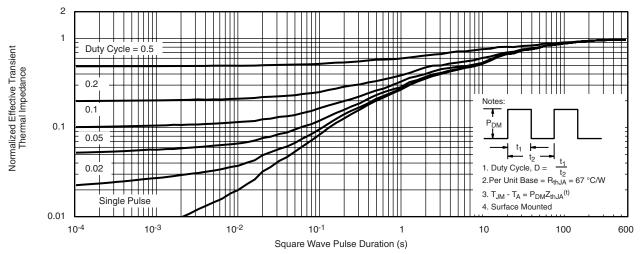
Document Number: 73539 S09-0226-Rev. B, 09-Feb-09

^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

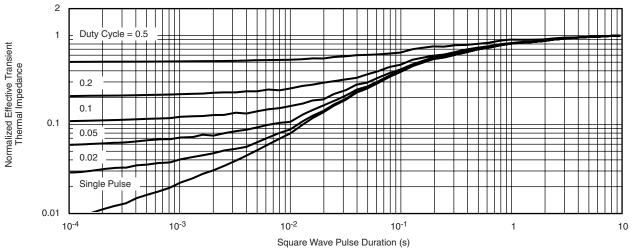
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

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